



October 17, 2006

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:	Serial No. 10/826,752	04/16/04
ROMEO EMMANUEL P. ALVAREZ		
"METHOD FOR FORMING A WAFER LEVEL CHIP SCALE PACKAGE, AND PACKAGE FORMED THEREBY"		
Grp. Art Unit: 2813		JAMES M. MITCHELL

## RESPONSE FINAL PATENT OFFICE ACTION

Dear Sir:

In response to the Final Office Action dated August 1, 2006, please amend the above-identified application for patent as follows:

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 1, 2006.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 11/1/06

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3  
of this paper.

Remarks/Arguments begin on page 6 of this paper.